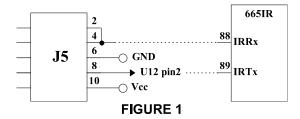


APPLICATION NOTE 5.15

MODIFYING SMSC'S SUPER I/O REV. B EVALUATION BOARDS FOR THE FDC37C665IR AND TEMIC IrDA INTERFACE By Rich Boz

To modify an SMSC Super I/O (FDC37C6XX) Rev. B Evaluation Board for the FDC37C665IR and a TEMIC IrDA interface follow the four steps, below.

- 1. Remove the UART 2 RS232 driver/receiver components, U8 and U12.
- 2. Re-wire the TEMIC Module Connector **J5** as follows (**Figure 1**):
 - a. Supply power to the TEMIC module by connecting VCC to J5 pin 10.
 - b. Connect the FDC37C665IR *IRTx* (pin 89) signal to the TEMIC module by wiring **U12 pin 2** to **J5 pin 8**.
 - c. Supply ground to the TEMIC module by connecting GND to J5 pin 6.
 - d. Connect the FDC37C665IR *IRRx* (pin 88) signal to the TEMIC module by wiring **J5 pin 2** to **J5 pin 4**.



- 3. Remove the RS232 receiver driver from the FDC37C665 *IRRx* signal (pin 88) by re-wiring **U9** as follows:
 - a. Disconnect **U9 pin 11** from board trace.
 - b. Connect **U9 pin 13** to former **U9 pin 11** board trace.
- 4. Supply power to the FDC37C665IR I/O Interface (pin 98) by connecting **JP13 pin 2** to **VCC**, do not Jumper **JP13**.

To use the TEMIC IrDA Transceiver Front-End with an FDC37C665IR-modified Super I/O Evaluation Board, connect the TEMIC Cable Connector to **J5** as shown in **Figure 2**.

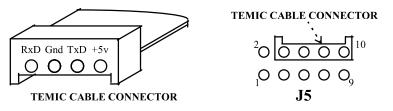


FIGURE 2



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